

Declaration of Storage Shelf Life

Please take note about the storage shelf life conditions for printed circuit boards.

Storage condition:

Product : Printed Circuit Boards
Packaging Method : vacuum package (not damaged) + dry pack
Storage conditions : Temperature: 25 +/- 3 °C
Humidity : 50 +/-6 %
Location : Packages should not be exposed to direct sunlight

Storage shelf life in terms of surface finishing:

Surface Finishing	Storage Life
ENTEK/OSP	3 months
Immersion Tin	6 months
Immersion Silver	3 months
Immersion Nickle/Gold	6 months
Flash Gold	6 months
HAL(lead free & tin/lead)	6 months

Remark: not damaged vacuum package + dry pack.

Usage of the bare PCB within the above specified storage shelf life:
Matrix guarantees the performance in accordance with IPC standards, and/or other standards that Matrix commits to meet, given the product is properly preserved in accordance with the above specified packaging method and storage conditions.

Usage of the bare PCB beyond the above specified storage shelf life:
Matrix declares that any further use of the product will probably cause defect/damage and/or potential defect/damage to the product, thus make the product less reliable.
Matrix is incapable to tell exactly what will happen to the product, and will no longer be responsible for any imperfection, defect and damage on the product, as well as those caused by the subsequent use of the product.

Please be informed that the above declaration is applicable to all the products that Matrix already has delivered and will deliver. If any of Matrix users is now storing Matrix products, please refer to the above statement, and make correct use of the product.